

Build Up HDI (Standard)	
HDI10_3+4+3_1,50_35_engl	10 - Layers Core: 0,36 mm Cu 35/35 μm
WE-Articel No.:	3 + 4 + 3
Customer:	



only CBT Schopfheim

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements	
Customer	WE					[μm]	[μm]	
	TOP/VS		Foil	12 μm	1) 1 x 1080	12 60		
	2		Foil	12 μm	1 x 1080	30 60		
	3		Foil	12 μm	1 x 1080	30 60		
	4		0,360 mm	35 μm		33 360		
	5		35 μm		2 x 1080	33 124		
	6		0,360 mm	35 μm		33 360		
	7		35 μm		1 x 1080	33 60		
	8		Foil	12 μm	1 x 1080	30 60		
	9		Foil	12 μm	1 x 1080	30 60		
	BOT/RS		Foil	12 μm	1) 1 x 1080	12 60		
			total material thickness: 1480				Note: Lamination thickness for Prepregs depending on layout characteristics.	

final lamination thickness:	1,50	+/-	0,13	mm		Date:	Engineer:
thickness with electro plated Cu:	1,59	+/-	0,16	mm			
total thickness with soldermask	1,65	+/-	0,18	mm			
customer requirement		+/-		mm	point:		

prepared: on 27.03.2006 by S. Keller	checked: on 04.05.2006 by M.Kress	approved: on 04.05.2006 by R.Schönholz	revision 00	page: 10+
---	--------------------------------------	---	----------------	-----------